

Appl. No. 09/922,479
Amtd. Dated February 1, 2008
Reply to Office Action of November 1, 2007

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SPECIFICATION AMENDMENTS

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Page 14, lines 14-18, replace the two paragraphs with the following:

Fig. 14 shows a configuration by means of which components containing semiconductor chips can be tested efficiently; and

Figs. 15A and 15B show various views of a component carrier employed in the configuration shown in Fig. 14; and

Fig. 16 shows a block diagram illustrating method steps.

Page 44 after line 3, insert the following:

Fig. 16 shows a block diagram illustrating steps of the method 100 of testing an integrated circuit IC. Step 110 includes providing a plurality of integrated circuits IC on at least one wafer W. Step 120 includes providing each integrated circuit IC with a self-test device BIST. Step 130 includes providing a self-test control device BIST that causes performance of the test of the integrated circuit IC. Step 140 includes either temporarily storing a plurality of integrated circuits IC or moving the self-test control device CM (See Fig. 12) together with the plurality of integrated circuits IC while simultaneously at least partially completing the testing of the plurality of integrated circuits IC with the

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self-test devices BIST. Step 150 includes using each self-test device BIST to write data into a test result memory REGB that is located on the integrated circuit IC with the self-test device BIST. Step 160 includes taking at least parts of an integrated circuit IC out of operation after the self-test device BIST that is located on the integrated circuit IC has tested the parts. The parts of the integrated circuit IC can be taken out of operation by preventing a clock signal from being supplied to the parts of the integrated circuit IC. This clock signal is needed to operate the integrated circuit IC. The parts of the integrated circuit IC can additionally or alternatively be taken out of operation by discontinuing a supply voltage to the parts of the integrated circuit. This supply voltage supplies the integrated circuit IC with power. Step 170 includes after testing the integrated circuit IC with the self-test device BIST, taking out of operation, components of the integrated circuit IC that are not needed to continue to store the data in the test result memory REGB. Step 180 includes after completing the testing, then connecting an integrated circuit IC to an external testing device ET that reads out results of the test and/or evaluates the results of the test.